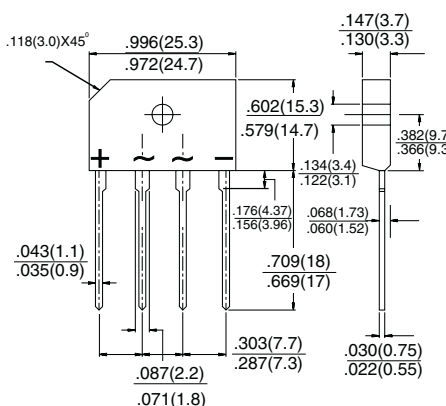



## 4.0 Amp. Glass Passivated Bridge Rectifier

<p style="text-align: center;"><b>Plastic Case</b></p>  <ul style="list-style-type: none"> <li>• <b>Mounting Instructions</b> <ul style="list-style-type: none"> <li>• High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>• Recommended mounting torque: 8 Kg.cm.</li> </ul> </li> </ul>	<p style="text-align: center;">Voltage 400 to 1000 V.</p> <p style="text-align: center;">Current 4.0</p> <div style="text-align: center;">  </div> <ul style="list-style-type: none"> <li>• <b>Glass Passivated Junction Chips.</b> <ul style="list-style-type: none"> <li>• Lead and polarity identifications.</li> <li>• Case: Molded Plastic.</li> <li>• Ideal for printed circuit board (P.C.B.).</li> <li>• High surge current capability.</li> <li>• The plastic material carries U/L recognition 94 V-O.</li> </ul> </li> </ul>
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Maximum Ratings, according to IEC publication No. 134

		<b>D3SB 40</b>	<b>D3SB 60</b>	<b>D3SB 80</b>	<b>D3SB 100</b>
$V_{RRM}$	Peak recurrent reverse voltage (V)	400	600	800	1000
$V_{RMS}$	Maximum RMS voltage (V)	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.0 A at 115°C Tc. 3.0 A at 40 °C			
$I_{FSM}$	10 ms. peak forward surge current (Jedec Method)	120 A			
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)	2000 V			
$I^2t$	Current squared time (rating for fusing) (1ms.<t<10ms. Tc = 25°C)	60 A <sup>2</sup> sec			
$T_j$	Operating temperature range	– 55 to + 150 °C			
$T_{stg}$	Storage temperature range	– 55 to +150 °C			

Electrical Characteristics at Tamb = 25°C

$V_F$	Max. forward voltage drop per diode at $I_F = 2.0 A$ $I_F = 4.0 A$	1.00V 1.10V
$I_R$	Max. instantaneous reverse current at $V_{RRM}$	5μA
$R_{th(j-c)}$ $R_{th(j-a)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink. Junction-Ambient. Without Heatsink.	5.5 °C/W 22 °C/W

## 4 Amp. Glass Passivated Bridge Rectifier

### Characteristic Curves

